

Photo DMOS-FET Relay

Description

The **LU610** is a 1-Form B solid state relay in a 4 pin SMD package that employs optically coupled MOSFET technology to provide 3750V/5000V of input to output isolation. The optically coupled input is controlled by a highly efficient GaAlAs infrared LED and MOS FETs on the output side.

Features

- Low driver power requirements (TTL/CMOS Compatible)
- Contact form: Normally-On (1b)
- Load voltage: 400V max.
- On-Resistance: 50Ω max.
- 3750Vrms Input/Output isolation
- Tape & Reel version available

Applications

- Telecommunications (PC, Electronic notepad)
- Measuring and Testing equipment
- Industrial control
- Security equipments
- High speed inspection machine

Outline Dimensions

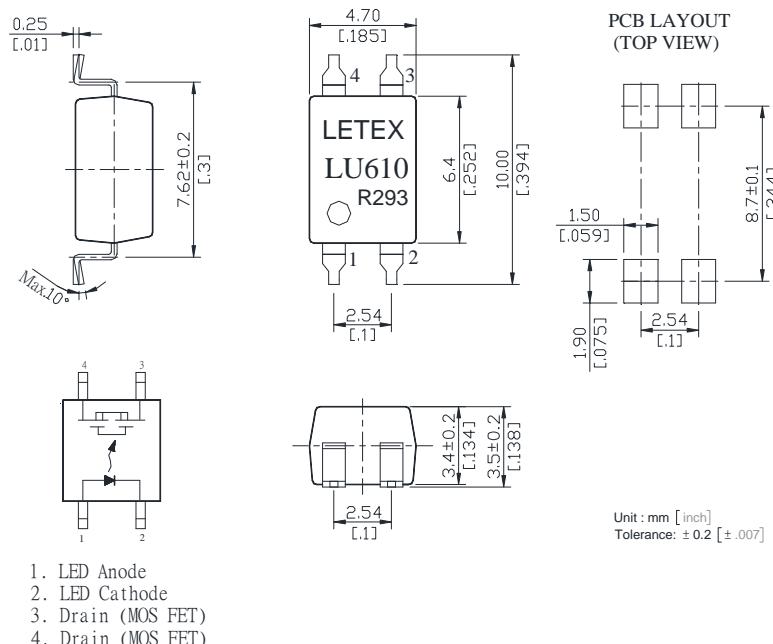


Photo DMOS-FET Relay Specifications

Part Name: LU610

(Load voltage: 400V / Load current: 120mA)

Absolute Maximum Ratings (Ambient Temperature: 25°C)

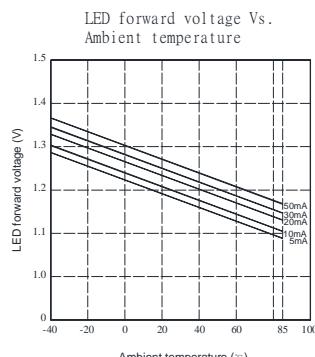
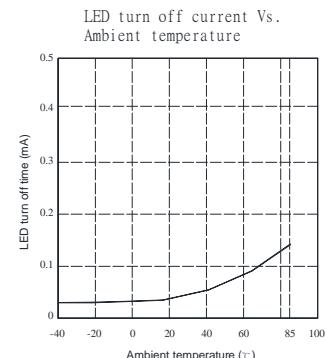
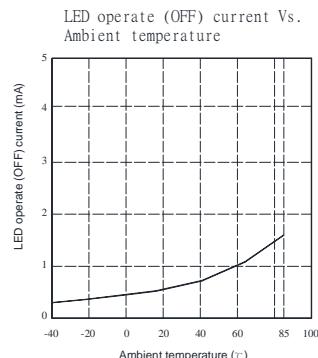
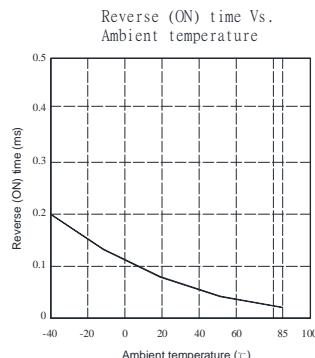
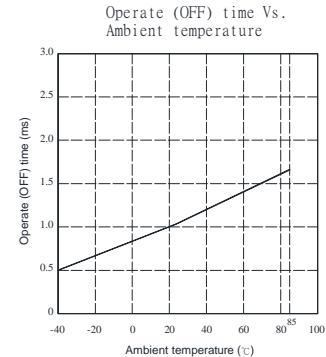
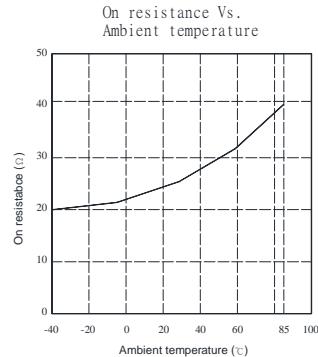
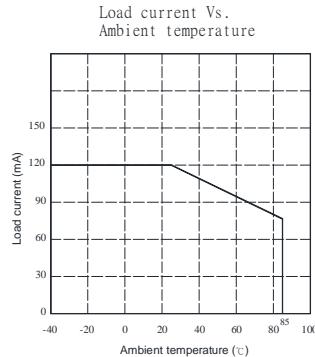
Item		Symbol	Value	Units	Note
Input	Continuous LED Current	I _F	50	mA	
	Peak LED Current	I _{FP}	1000	mA	f=100Hz, duty=1%
	LED Reverse Voltage	V _R	5	V	
	Input Power Dissipation	P _{In}	75	mW	
Output	Load Voltage	V _L	400	V(AC peak or DC)	
	Load Current	I _L	120	mA	
	Peak Load Current	I _{Peak}	0.3	A	1ms(1 pulse)
	Output Power Dissipation	P _{out}	500	mW	
Total Power Dissipation		P _T	550	mW	
I/O Breakdown Voltage		V _{I/O}	3750	Vrms	RH=60%, 1min
I/O Breakdown Voltage(Suffix-V)		V _{I/O}	5000	Vrms	RH=60%, 1min
Operating Temperature		T _{opr}	-40 to +85	°C	
Storage Temperature		T _{tsg}	-40 to +100	°C	
Pin Soldering Temperature		T _{sol}	260	°C	10 sec max.

Electrical Specifications (Ambient Temperature: 25°C)

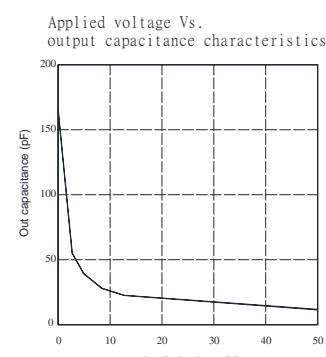
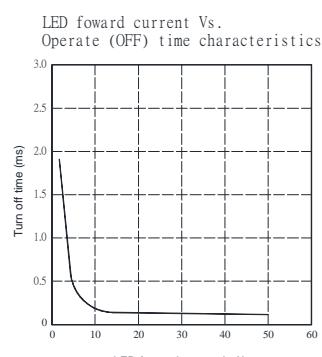
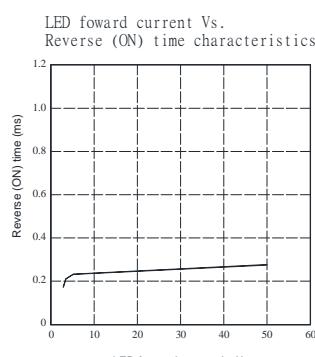
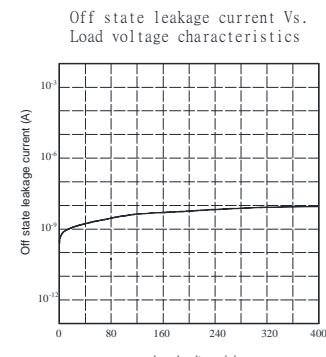
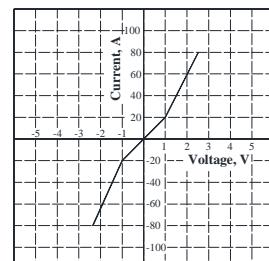
Item		Symbol	MIN.	TYP.	MAX.	Units	Conditions
Input	LED Forward Voltage	V _F		1.2	1.5	V	I _F =10mA
	Operation LED Current	I _{Fon}		0.5	5.0	mA	
	Recovery LED Current	I _{Foff}		0.35	0.5	mA	
	Recovery LED Voltage	V _{Foff}	0.5			V	
Output	On-Resistance	R _{on}		20	50	Ω	I _F =0mA, I _L =100mA, Time to flow is within 1 sec.
	Off-State Leakage Current	I _{Leak}			10	uA	I _F =5mA, V _L =400V
	Output Capacitance	C _{out}		165		pF	I _F =5mA, V _L =0, f=1MHz
Transistor	Turn-On Time	T _{on}		0.02	1.0	ms	I _F =10mA, I _L =100mA
	Turn-Off Time	T _{off}		0.5	3.0	ms	
Coupled	I/O Isolation Resistance	R _{I/O}	10 ¹⁰			Ω	DC500V
	I/O Capacitance	C _{I/O}		0.8		pF	f=1MHz



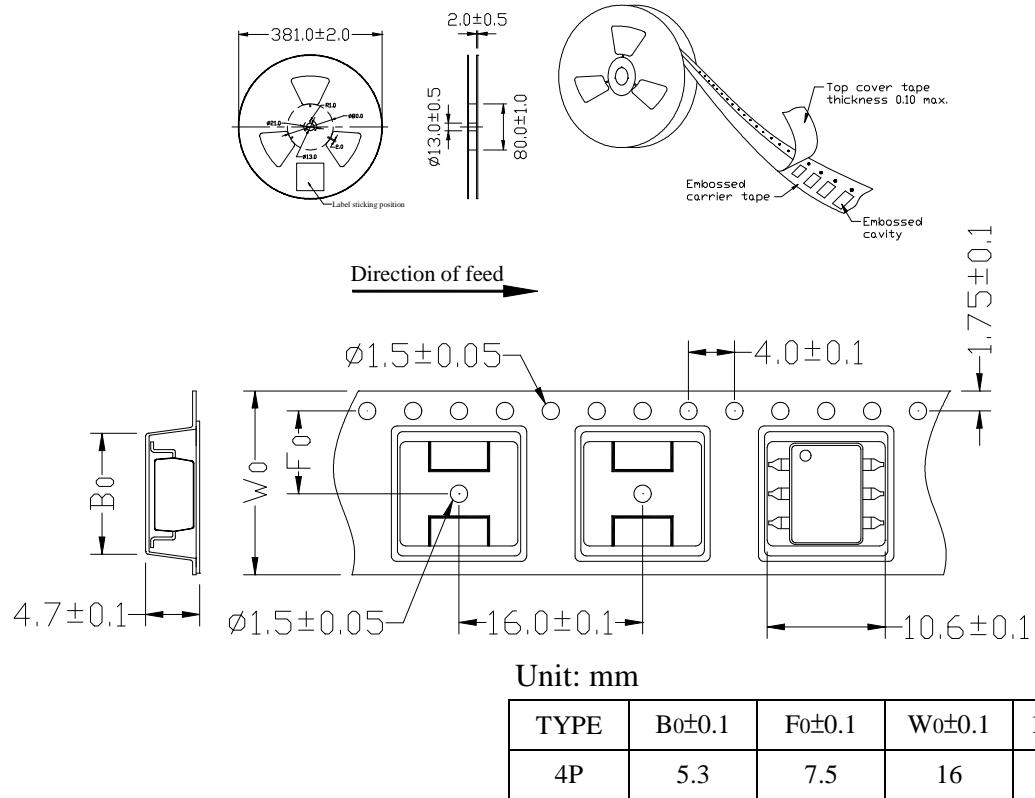
Reference Data



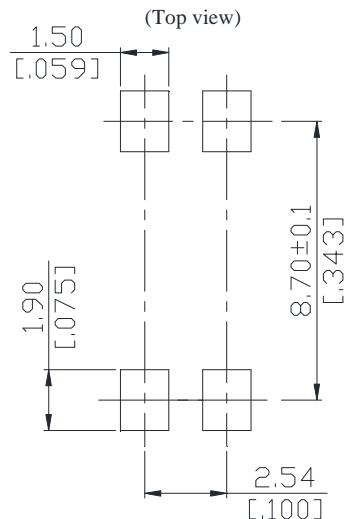
Voltage Vs. current characteristics
of output at MOS portion



Taping Specifications for Surface Mount Devices

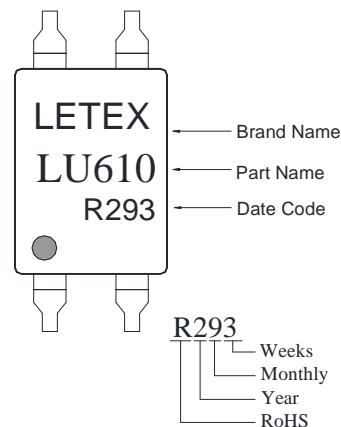


Recommended Mounting Pad



Marking

(Each photo MOS Relay shall be marked with the following information)



- Note:
- There shall be leader of 230 mm minimum which may consist of carrier and or cover tape follower by a minimum of 160 mm of carrier tape sealed with cover tape.
 - There shall be a minimum of 160 mm of empty component pockets sealed with cover tape.
 - Devices are pockets in accordance with EIA standard EIA-481-A and specifications given above.

